

What is claimed is:

1. A substrate support, comprising:
a ceramic body;
an electrode disposed in the ceramic body;
a ground plate disposed in the ceramic body, wherein portions of the ground plate are interdigitated with portions of the electrode; and
one or more heating elements disposed within the ceramic body.
2. The substrate support of claim 1, wherein
the portions of the ground plate are coplanar with the electrode.
3. The substrate support of claim 1, further comprising a ground shield assembly disposed in the ceramic body, the ground shield assembly comprises:
one or more ground leads;
a first conductive member opposite the one or more ground leads;
a second conductive member extending between the one or more ground leads and the first conductive member; and
a third conductive member opposite the second conductive member and extending between the one or more ground leads and the first conductive member.
4. The substrate support of claim 3, wherein the first conductive member is radially outward of the one or more ground leads and the first conductive member extends from the second conductive member to the third conductive member.
5. The substrate support of claim 1, wherein the ground plate comprises a plurality of holes defining the portions of the ground plate, and the portions of the electrode are positioned within the plurality of holes.
6. The substrate support of claim 1, wherein the portions of the ground plate surround the portions of the electrode to form one or more coaxial structures.
7. A substrate support, comprising:
a body having a first surface and a second surface opposite the first surface, the first surface comprising a plurality of mesas and a

plurality of valleys, each of the plurality of valleys disposed between at least two of the plurality of mesas;
an electrode disposed in the body, a plurality of portions of the electrode aligned with the plurality of mesas;
a ground plate disposed in the body, wherein a plurality of portions of the ground plate are aligned with the plurality of valleys; and
one or more heating elements disposed in the body.

8. The substrate support of claim 7, further comprising a ground shield assembly disposed in the body, the ground shield assembly comprises:

one or more ground leads;
a plurality of first members opposite and radially outward of the one or more ground leads;
a plurality of second members, each of the plurality of second members extending from the one or more ground leads to the plurality of first members; and
a plurality of third members opposite the plurality of second members, each of the plurality of third members extending from the one or more ground leads to the plurality of first members.

9. The substrate support of claim 8, wherein an impedance of the ground shield assembly is less than an impedance of one or more power leads coupled to the electrode.

10. The substrate support of claim 7, wherein the electrode is monopolar.

11. The substrate support of claim 7, wherein the electrode is bipolar.

12. The substrate support of claim 7,
wherein the portions of the ground plate and the portions of the electrode are coplanar.

13. The substrate support of claim 7, wherein the ground plate comprises a plurality of holes defining the portions of the ground plate, the portions of the electrode positioned within the plurality of holes.

14. The substrate support of claim 7, wherein the portions of the ground plate surround the portions of the electrode to form one or more coaxial

structures.

15. A process chamber, comprising:
 - a chamber body and a lid defining a process volume therein;
 - a showerhead disposed in the process volume and coupled to the lid;
 - a stem extending from a bottom of the chamber body opposite the lid;
 - and
 - a substrate support disposed in the process volume on the stem, the substrate support comprising:
 - a body;
 - an electrode disposed in the body;
 - a ground plate disposed in the body, wherein portions of the ground plate are interdigitated with portions of the electrode; and
 - one or more heating elements disposed within the body.
16. The process chamber of claim 15,
 - wherein the portions of the ground plate are coplanar with the portions of the electrode.
17. The process chamber of claim 16, further comprising a ground shield assembly disposed in the body, the ground shield assembly comprises:
 - one or more ground leads;
 - a plurality of first member opposite and radially outward of the one or more ground leads;
 - a plurality of second member extending from the one or more ground leads to the first member; and
 - a plurality of third member extending from the one or more ground leads to the first member and opposite the second member.
18. The process chamber of claim 17, wherein the ground shield assembly forms a lattice structure surrounding the one or more heating elements.
19. The process chamber of claim 15, wherein the ground plate comprises a plurality of holes defining the portions of the ground plate, the portions of the electrode positioned within the plurality of holes.
20. The process chamber of claim 15, wherein the portions of the ground

plate surround the portions of the electrode to form one or more coaxial structures.